

TEP-1010-BSW MODULAR HMI PRODUCT MANUAL

(TEP-1010-BSW)

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TABLE OF CONTENTS

1. Introduction	5
1.1. General Care and Maintenance	5
2. TEP-1010-BSW Product Overview	6
2.1. Functional Block Diagram	6
2.2. Dimensions	7
2.3. Device Cut-out Dimensions For Mounting Though a Panel	8
2.4. External Connectors	9
2.5. Internal Board Connectors	10
2.5.1. Galvanic Isolated (TEP1010-xxxxx-Rxx-Lxxx-XG21- xxxx-xxxx)	10
2.5.2. Non-Galvanic Isolated (TEP1010-xxxxx-Rxx-Lxxx-XS21- xxxx-xxxx)	11
2.5.3. Board View Without the Power and I/O Expansion Modules	12
3. External Connectors	13
3.1. LED Light Indicator	13
3.2. Micro-SIM Connector	13
3.3. MicroSD Connector	13
3.4. USB OTG (Type-C) Connector	14
3.5. Gigabit Ethernet Interface (LAN1/LAN2)	14
3.6. USB 2.0 Host Connectors	14
3.7. USB 3.0 Host Connectors	15
3.8. miniDP (Mini DisplayPort) Connector	15
3.9. HDMI (High Definition Multi-Media Interface) Connector	15
3.10. Audio Connectors	15
3.11. RST Button	15
3.12. PWR Button	15
3.13. Power Input Connector	16
3.14. Antenna Holes	16
3.15. Galvanic Isolated Connectors (TEP1010-xxxxx-Rxx-Lxxx-XG21-xxxx-xxx-xxxx	() (optional)16
3.15.1. Galvanic Isolated Digital I/O Connectors (GPIO1/GPIO2) (optional)	17
3.15.2. Galvanic Isolated Serial Port (RS-XXX) (optional)	18
3.16. Non-Galvanic Isolated Connectors (TEP1010-xxxxx-Rxx-Lxxx-XS21- xxxx-xxx	(-xxxx) (optional).19
3.16.1. Non-Galvanic Isolated Digital I/O Connectors (GPIO1/GPIO2) (optional)	20
3.16.2. Non-Galvanic Isolated Serial Port (RS-XXX) (optional)	21
4. Internal Connectors and Expansion Options	22
4.1. M.2 KEY-B Slots	22
4.2. SATA 3.0 and SATA Power Connectors	22
4.3. RTC Battery Connector	23

4.4. M.2 KEY-E Slot
4.5. CMOS Jumper23
4.6. SO-DIMM DDR3L Slot23
4.7. Internal Stereo Speaker Connectors24
5. BIOS Setup
5.1. Entering and Exiting BIOS25
5.2. BIOS Setup Screens Overview25
5.2.1. Main
5.2.2. Chipset
5.2.3. Advanced
5.2.4. Boot
5.2.5. Security
5.2.6. Save & Exit
6. Mounting
6.1. VESA Mounting
6.2. Rear Mounting and Mounting Clips Installation35
6.3. Surface Mounting
7. Ordering Information
7.1. Custom Part Number Rule
7.2. Standard Package Contents
8. Important Notice
8. DISCLAIMER

1. Introduction

1.1. General Care and Maintenance

Your device is a product of superior design and craftsmanship and should be treated with care.

The following suggestions will help you.

- Keep the device dry. Precipitation, humidity, and all types of liquids or moisture can contain minerals that will corrode electronic circuits. If your device does get wet, allow it to dry completely.
- Do not use or store the device in dusty or dirty areas. Its parts and electronic components can be damaged.
- Do not store the device in hot areas. High temperatures can shorten the life of electronic devices, damage batteries, and warp or melt certain plastics.
- Do not store the device in cold areas. When the device returns to its normal temperature, moisture can form inside the device and damage electronic circuit boards.
- Do not open the device while power is on. Otherwise electrical shock may result.
- Do not drop, knock, or shake the device. Rough handling can break internal circuit boards and fine mechanics.
- Do not use harsh chemicals, cleaning solvents, or strong detergents to clean the device.
- Do not paint the device. Paint can clog the parts and prevent proper operation.
- Unauthorized modifications or attachments could damage the device and may violate regulations governing radio devices.

These suggestions apply equally to your device, battery, charger, or any enhancement. If any device is not working properly, take it to the nearest authorized service facility for service. Regulatory information



Disposal of Waste Equipment by Users in Private Household in the European Union This symbol on the product or on its packaging indicates that this product must not be disposed of with your other household waste. Instead, it is your responsibility to dispose of your waste equipment by handing it over to a designated collection point for the recycling of waste electrical and electronic equipment. The separate collection and recycling of your waste equipment at the time of disposal will help to conserve natural resources and ensure that it is recycled in a manner that protects human health and the environment. For more information about where you can drop off your waste equipment

for recycling, please contact your local city office, your household waste disposal service or the shop where you purchased the product.



We hereby declare that the product is in compliance with the essential requirements and other relevant provisions of European Directive 1999/5/EC (radio equipment and telecommunications terminal equipment Directive).

2. TEP-1010-BSW Product Overview

2.1. Functional Block Diagram



2.2. Dimensions

The following figure shows the TEP-1010-BSW dimensions (unit: mm):



2.3. Device Cut-out Dimensions For Mounting Though a Panel

The TEP-1010-BSW can be mounted on the front or the back of the panel. In order to mount it from the front, a nominal rectangular cutout must be made in the panel. The following drawing shows the dimensions of the cut-out area (unit: mm):



2.4. External Connectors

The TEP-1010-BSW has a number of external connectors. Bottom view:



External Connectors:

No.	Description	No.	Description
1	LED Light indicator	12	3.5mm jack Line out
2	Micro-SIM cardslot	13	3.5mm jack Line in
3	MicroSD cardslot	14	3.5mm jack Mic in
4	USB OTG (Type-C) connector	15	Reset button
5	LAN2 RJ45 connector	16	Power button
6	USB 2.0 Host connector	17	Power Input connector
7	USB 2.0 Host connector	18	LAN1 RJ45 connector (PoE)
8	USB 3.0 Host connector	19	GPIO1 connector (optional)
9	USB 3.0 Host connector	20	GPIO2 connector (optional)
10	miniDP connector	21	RS-XXX (Serial Port) connector (optional)
11	HDMI connector		

2.5. Internal Board Connectors

The TEP-1010-BSW has several connectors, switches and internal expansion options.

2.5.1. Galvanic Isolated (TEP1010-xxxxx-Rxx-Lxxx-XG21- xxxx-xxxx)

Rear view (opened device) with the galvanic isolated I/0 Expansion module:



Internal Connectors and Switches:

No.	Description	No.	Description
А	M.2 KEY-B slot (USB 2.0)	F	CMOS jumper
В	SATA Power connector	G	SO-DIMM DDR3L slot
С	SATA 3.0 connector	H*	SW1 DIP switch
D	RTC Battery connector	*	SW3 Terminator Resistor DIP switch
E	M.2 KEY-E slot (PCIe + USB 2.0)	J*	SW2 Terminator Resistor DIP switch

NOTE: Items marked with * are available on the galvanic isolated I/O Expansion module (TXB-I2-GS2-GG8) (optional).

2.5.2. Non-Galvanic Isolated (TEP1010-xxxxx-Rxx-Lxxx-XS21- xxxx-xxxx)

Rear view (opened device) with the non-galvanic isolated I/0 Expansion module:



Internal Connectors and Switches:

No.	Description	No.	Description
А	M.2 KEY-B slot (USB 2.0)	ш	M.2 KEY-E slot (PCIe + USB 2.0)
В	SATA Power connector	F	CMOS jumper
С	SATA 3.0 connector	G	SO-DIMM DDR3L slot
D	RTC Battery connector	H*	SW1 Terminator Resistor DIP switch

NOTE: Items marked with * are available on the non-galvanic isolated I/O Expansion module (TXB-I2-S2-C2-G8) (optional).

2.5.3. Board View Without the Power and I/O Expansion Modules

Rear view (opened device) without the Power and I/O Expansion modules:



Internal Connectors and Switches:

No.	Description	No.	Description
А	M.2 KEY-B slot (USB 2.0)	G	SO-DIMM DDR3L slot
В	SATA Power connector	H*	M.2 KEY-B slot (SATA + USB 2.0)
С	SATA 3.0 connector	*	Internal R speaker connector
D	RTC Battery connector	J*	Internal L speaker connector
Е	M.2 KEY-E slot (PCIe + USB 2.0)	K*	I/O Expansion module connector
F	CMOS jumper	L*	Power Expansion module connector

NOTE: Items marked with * are accessible only after removing the Power and I/O Expansion modules.

3. External Connectors

3.1. LED Light Indicator

The TEP-1010-BSW has one Power LED Light indicator. The Power LED Light indicator is lit, when the system is powered on.

LED #	Color	Power on	Power off
1	Green	ON	OFF

3.2. Micro-SIM Connector

The TEP-1010-BSW features an external Micro-SIM cardslot for use by 3G/4G/LTE wireless module.

NOTE: This cardslot can be only used by a M.2 KEY-B 3G/4G/LTE module installed into the 3G/LTE connector. The 3G/LTE connector can be found at location "A" in chapter <u>4. Internal Connectors and Expansion Options</u> of this manual. No M.2 KEY-B 3G/LTE module is included in this device (must be purchased separately, not sold by TechNexion).

3.3. MicroSD Connector

The TEP-1010-BSW features a standard microSD cardslot which is connected to the Intel processor's (Atom x5-E8000 / Pentium N3710) integrated "Ultra Secured Digital Host Controller" (uSDHC).

The following main features are supported by uSDHC:

- Compatible with the MMC System Specification version 4.2/4.3/4.4/4.41/5.0.
- Conforms to the SD Host Controller Standard Specification version 3.0.
- Compatible with the SD Memory Card Specification version 3.0 and supports the "Extended Capacity SD Memory Card".
- Compatible with the SDIO Card Specification version 3.0.
- Supports 1-bit / 4-bit SD and SDIO modes

The MMC/SD/SDIO host controller can support a single MMC / SD / SDIO card or device.

3.4. USB OTG (Type-C) Connector

The TEP-1010-BSW has one USB OTG Type-C connector (USB 2.0 and USB 3.0 signals) that can be used to connect a host computer to the unit for programming and update purposes.

A2 A3 A4 A5 A6 A7 A8 A9 A10 A11 A12

		B12 B11 B10 B9 B8 B	' B6 B5 B4	4 B3 B2 B1	
Pin #	Signal	Description	Pin #	Signal	Description
A1	GND	Ground	B1	GND	Ground
A2	TX1+	SS differential pair #1 signal	B2	TX2+	SS differential pair #3 signal
A3	TX1-		B3	TX2-	
A4	VBUS	5V Universal Serial Bus Power	B4	VBUS	5V Universal Serial Bus Power
A5	CC1	OTG detection signal port 1	B5	CC2	OTG detection signal port 2
A6	USB_D+	USB differential pair signal	B6	USB_D+	USB differential pair signal
A7	USB_D-	port 1	B7	USB_D-	port 2
A8	SBU1	Sideband use port 1	B8	SBU1	Sideband use port 2
A9	VBUS	5V Universal Serial Bus Power	B9	VBUS	5V Universal Serial Bus Power
A10	RX2-	SS differential pair #4 signal	B10	RX1-	SS differential pair #2 signal
A11	RX2+		B11	RX1+	-
A12	GND	Ground	B12	GND	Ground

3.5. Gigabit Ethernet Interface (LAN1/LAN2)

The TEP-1010-BSW comes with two Gigabit Ethernet RJ45 connectors. LAN1 connector can support 802.3at Power over Ethernet functionality if configured with the PoE power option (TEP1010-xxxx-Rxx-LPOE-xxxx-xxxx-xxxx) by connecting it to an 802.3at compliant PoE switch or power injector.



LAN1 / LAN2:

Pin #	1000 Mbps	100 Mbps	10 Mbps
1	MDI0+	Transmit Data+	Transmit Data+
2	MDI0-	Transmit Data-	Transmit Data-
3	MDI1+	Receive Data+	Receive Data+
4	MDI2+		
5	MDI2-		
6	MDI1-	Receive Data-	Receive Data-
7	MDI3+		
8	MDI3-		

3.6. USB 2.0 Host Connectors

The TEP-1010-BSW has two USB 2.0 Host connectors (USB 2.0 signals only) to connect to a USB peripheral such as a keyboard, mouse, USB storage device or USB hub.

3.7. USB 3.0 Host Connectors

The TEP-1010-BSW has two USB 3.0 Host connectors (USB 2.0 and USB 3.0 signals) to connect to a USB peripheral such as a keyboard, mouse, USB storage device or USB hub.

3.8. miniDP (Mini DisplayPort) Connector

The miniDP interface available on the TEP-1010-BSW is based on Intel HD Graphics engine integrated into the Intel Braswell processor and can be configured to support a secondary display.

The miniDP supports the following standards & features:

- DisplayPort 1.1a
- DisplayPort Content Protection
- High-bandwidth Digital Content Protection
- Refresh rate up to 240 FPS for 1080p at 24 bpp
- Support for up to 4k x 2k and 3D video formats
- Support for up to 48 bpp Color Depth

3.9. HDMI (High Definition Multi-Media Interface) Connector

The HDMI interface available on the TEP-1010-BSW is based on Intel HD Graphics engine integrated into the Intel Braswell processor and can be configured to support a secondary display.

The HDMI supports the following standards & features:

- High-Definition Multimedia Interface Specification, Version 1.4b
- Digital Visual Interface, Revision 1.0
- HDMI Compliance Test Specification, Version 1.4b
- Support for up to 720p at 100Hz and 720i at 200Hz or 1080p at 60Hz and 1080i/720i at 120Hz HDTV display resolutions and up to QXGA graphic display resolutions.
- Support for 4k x 2k and 3D video formats
- Support for up to 16-bit Deep Color modes

3.10. Audio Connectors

The TEP-1010-BSW has three external 3.5mm stereo audio jacks.

Color Code	Signal	Description
Green	L/R Line out	Audio output
Blue	L/R Line in	Audio input
Pink	Mic in	Microphone input

3.11. RST Button

The TEP-1010-BSW features a "RST" button for system reset.

3.12. PWR Button

The TEP-1010-BSW features a "PWR" button for system power on. System is turned on when button is pressed, and the Power LED Light indicator lit. If the system hangs, depressing the button for 5 seconds powers down the system.

3.13. Power Input Connector

The TEP-1010-BSW can be powered either over the DC INPUT connector or PoE (optional) over the RJ45 LAN1 port.

NOTE: Do not power the unit by DC input when you apply power over the Power over Ethernet (RJ45)!



Pin #	Signal	Description
1	GND	Ground
2	VCC	DC Voltage input (12V/24V/8~36VDC)

Header on TEP-1010-BSW: Molex 43045-0200 (2-pin Micro-Fit 3.0). Cable receptacle: Molex 43025-0200 (2-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.14. Antenna Holes

There are six antenna holes available (two each on the left side, on the right side and on the top side). They come fitted with breakaway metal tabs. In order to utilize them, the tabs must be removed by carefully using pincers or pliers.

3.15. Galvanic Isolated Connectors (TEP1010-xxxxx-Rxx-Lxxx-XG21-xxxx-xxxxxxx) (optional)

This product is available with three optional connectors: GPIO1, GPIO2, and RS-XXX that can be ordered in either galvanic isolated or non-galvanic isolated versions. The TEP1010-xxxx-Rxx-Lxxx-XG21-xxxx-xxxx has three optional galvanic isolated connectors: GPIO1, GPIO2, and RS-XXX.

Top view of the galvanic isolated I/0 Expansion module (TXB-I2-GS2-GG8):



No.	Description	No.	Description
А	SW1 DIP switch	С	SW2 Terminator Resistor DIP switch
В	SW3 Terminator Resistor DIP switch		

3.15.1. Galvanic Isolated Digital I/O Connectors (GPIO1/GPIO2) (optional)

The galvanic isolated GPIO Expansion headers have the following pinout:

8	7	6	5
4	3	2	1
			$\overline{}$

GPIO1:

Pin	Signal	Description	Voltag	е		Curr	Interfa	Control	CPU
#			Min.	Тур.	Max.	ent Max.	ce Source	ler	Pin #
1	GPIO1A	DIG_IN1	4.75V	5V	5.25V	300 mA	LPC	Fintek F81804	GPIO12
2	GPIO1B	DIG_IN2	4.75V	5V	5.25V	300 mA	LPC	Fintek F81804	GPIO17
3	GND_DIO	Ground for digital I/O							
4	GND	Common Ground							
5	GPIO1C	DIG_OUT5	11.21 V	11.8V	12.39 V	125 mA	LPC	Fintek F81804	GPIO91
6	GPIO1D	DIG_OUT6	11.21 V	11.8V	12.39 V	125 mA	LPC	Fintek F81804	GPIO94
7	VCC_DIO	Supply input for digital I/O	5V		12.39 V	300 mA			
8	VCC	Supply output	11.4V	12V	12.6V	300 mA			

GPIO2:

Pin	Signal	Description	Voltag	е		Curr	Interfa	Control	CPU
#			Min.	Тур.	Max.	ent Max.	ce Source	ler	Pin #
1	GPIO2A	DIG_IN1	4.75V	5V	5.25V	300 mA	LPC	Fintek F81804	GPIO93
2	GPIO2B	DIG_IN2	4.75V	5V	5.25V	300 mA	LPC	Fintek F81804	GPIO16
3	GND_DIO	Ground for digital I/O							
4	GND	Common Ground							
5	GPIO2C	DIG_OUT5	11.21 V	11.8V	12.39 V	125 mA	LPC	Fintek F81804	GPIO92
6	GPIO2D	DIG_OUT6	11.21 V	11.8V	12.39 V	125 mA	LPC	Fintek F81804	GPIO15
7	VCC_DIO	Supply input for digital I/O	5V		12.39 V	300 mA			
8	VCC	Supply output	11.4V	12V	12.6V	300 mA			

Header on TEP-1010-BSW: Molex 43045-0800 (8-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-0800 (8-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.15.2. Galvanic Isolated Serial Port (RS-XXX) (optional)

The dual 4-wire galvanic isolated serial port can be configured as follows: the primary serial port can only be used as a standard RS-232. The secondary port can be configured either as RS-232, or RS-422 or RS-485. This serial port is set by default as RS-232. Setting the TEP-1010-BSW in other mode will require to open the device and adjust the internal SW1 DIP and SW3 Terminator Resistor DIP switch settings on the TEP I/O Expansion board. The SW1 DIP switch can be found at location "A" and SW3 DIP switch at location "B" in chapter <u>3.15. Galvanic Isolated Connectors (TEP1010-xxxxx-Rxx-Lxxx-XG21-xxxx-xxxx</u>) (optional) of this manual.

SW1:

Pin #	RS-232 (default)	RS-422	RS-485
1-8	ON	OFF	OFF
2-7	OFF	ON	OFF
3-6	OFF	OFF	ON
4-5	-	-	-

SW3:

Pin #	ON	OFF
1-8	Enable RS-485 Terminator Resistor	Disable RS-485 Terminator Resistor
2-7	Enable RS-422 Terminator Resistor	Disable RS-422 Terminator Resistor
3-6	-	-
4-5	-	-



RS-232 + RS-232 (default setup):

Pin #	Signal	Description	Device
1	GND	Ground	
2	SERIAL1A_TXD	Port#1A Transmit data (output)	COM1
3	SERIAL1A_RXD	Port#1A Receive data (input)	COM1
4	SERIAL1A_RTS	Port#1A Request-to-send (output)	COM1
5	SERIAL1A_CTS	Port#1A Clear-to-send (input)	COM1
6	GND	Ground	
7	SERIAL1B_TXD	Port#1B Transmit data (output)	COM2
8	SERIAL1B_RXD	Port#1B Receive data (input)	COM2
9	SERIAL1B_RTS	Port#1B Request-to-send (output)	COM2
10	SERIAL1B_CTS	Port#1B Clear-to-send (input)	COM2

RS-232 + RS-422:

Pin #	Signal	Description	Device
1~5	SERIAL1A	Identical as above	COM1
6	GND	Ground	
7	SERIAL1B_TXD+	RS-422 Transmit positive data signal (output)	COM2
8	SERIAL1B_RXD-	RS-422 Receive negative data signal (input)	COM2
9	SERIAL1B_RXD+	RS-422 Receive positive data signal (input)	COM2
10	SERIAL1B_TXD-	RS-422 Transmit negative data signal (output)	COM2

RS-232 + RS-485:

Pin #	Signal	Description	Device
1~5	SERIAL1A	Identical as above	COM1
6	GND	Ground	
7	SERIAL1B+	RS-485 positive data signal	COM2
8	NC		
9	NC		
10	SERIAL1B-	RS-485 negative data signal	COM2

Header on TEP-1010-BSW: Molex 43045-1000 (10-pin Micro-Fit 3.0). Cable receptacle: Molex 43025-1000 (10-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.16. Non-Galvanic Isolated Connectors (TEP1010-xxxxx-Rxx-Lxxx-XS21- xxxxxxx-xxxx) (optional)

This product is available with three optional connectors: GPIO1, GPIO2, and RS-XXX that can be ordered in either galvanic isolated or non-galvanic isolated versions. The TEP1010-xxxx-Rxx-Lxxx-XS21-xxxx-xxx has three optional non-galvanic isolated connectors: GPIO1, GPIO2, and RS-XXX.

Top view of the non-galvanic isolated I/0 Expansion module (TXB-I2-S2-G8):



No.	Description	No.	Description
А	SW1 Terminator Resistor DIP switch		

3.16.1. Non-Galvanic Isolated Digital I/O Connectors (GPIO1/GPIO2) (optional)

The non-galvanic isolated GPIO Expansion headers have the following pinout:



GPIO1:

Pin	Signal	Description	Voltage	е		Curr	Interfa	Control	CPU
#			Min.	Тур.	Max.	ent Max.	ce Source	ler	Pin #
1	GPIO1A	DIG_IN1/OUT1	3.14V	3.3V	3.46V	300 mA	LPC	Fintek F81804	GPIO12
2	GPIO1B	DIG_IN2/OUT2	3.14V	3.3V	3.46V	300 mA	LPC	Fintek F81804	GPIO17
3	NC								
4	GND	Common Ground							
5	GPIO1C	DIG_IN5/OUT5	3.14V	3.3V	3.46V	300 mA	LPC	Fintek F81804	GPIO91
6	GPIO1D	DIG_IN5/OUT6	3.14V	3.3V	3.46V	300 mA	LPC	Fintek F81804	GPIO94
7	NC								
8	VCC	Supply output	11.4V	12V	12.6V	300 mA			

GPIO2:

Pin	Signal	Description	Voltage	е		Curr	Interfa	Control	CPU
#			Min.	Тур.	Max.	ent Max.	ce Source	ler	Pin #
1	GPIO2A	DIG_IN1/OUT1	3.14V	3.3V	3.6V	300 mA	LPC	Fintek F81804	GPIO93
2	GPIO2B	DIG_IN2/OUT2	3.14V	3.3V	3.6V	300 mA	LPC	Fintek F81804	GPIO16
3	NC								
4	GND	Common Ground							
5	GPIO2C	DIG_IN5/OUT5	3.14V	3.3V	3.6V	300 mA	LPC	Fintek F81804	GPIO92
6	GPIO2D	DIG_IN5/OUT6	3.14V	3.3V	3.6V	300 mA	LPC	Fintek F81804	GPIO15
7	NC								
8	VCC	Supply output	11.4V	12V	12.6V	300 mA			

Header on TEP-1010-BSW: Molex 43045-0800 (8-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-0800 (8-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.16.2. Non-Galvanic Isolated Serial Port (RS-XXX) (optional)

The dual 4-wire non-galvanic isolated serial port are configured as follows: the primary and the secondary serial port can only be used as a standard RS-232.



RS-232 + RS-232:

Pin #	Signal	Description	Device
1	GND	Ground	
2	SERIAL1A_TXD	Port#1A Transmit data (output)	COM1
3	SERIAL1A_RXD	Port#1A Receive data (input)	COM1
4	SERIAL1A_RTS	Port#1A Request-to-send (output)	COM1
5	SERIAL1A_CTS	Port#1A Clear-to-send (input)	COM1
6	GND	Ground	
7	SERIAL1B_TXD	Port#1B Transmit data (output)	COM2
8	SERIAL1B_RXD	Port#1B Receive data (input)	COM2
9	SERIAL1B_RTS	Port#1B Request-to-send (output)	COM2
10	SERIAL1B_CTS	Port#1B Clear-to-send (input)	COM2

Header on TEP-1010-BSW: Molex 43045-1000 (10-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-1000 (10-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

4. Internal Connectors and Expansion Options

Rear view (opened device) without the Power and I/O Expansion modules:



Internal Connectors and Switches:

No.	Description	No.	Description
А	M.2 KEY-B slot (USB 2.0)	G	SO-DIMM DDR3L slot
В	SATA Power connector	Н	M.2 KEY-B slot (SATA + USB 2.0)
С	SATA 3.0 connector	*	Internal R speaker connector
D	RTC Battery connector	J*	Internal L speaker connector
E	M.2 KEY-E slot (PCIe + USB 2.0)	K*	I/O Expansion module connector
F	CMOS jumper	L*	Power Expansion module connector

NOTE: Items marked with * are accessible only after removing the Power and I/O Expansion modules.

4.1. M.2 KEY-B Slots

The TEP-1010-BSW has two internal M.2 KEY-B connectors: 3G/LTE and SATA (Marked A and H respectively). M.2 3G/LTE connector supports USB 2.0 signals only. On the other hand, M.2 SATA connector supports SATA and USB 2,0 signals.

NOTE: M.2 3G/LTE connector can be only used by a M.2 KEY-B 3G/LTE module installed into the M.2 connector (Marked A). No M.2 KEY-B 3G/LTE module is included in this device (must be purchased separately, not sold by TechNexion).

4.2. SATA 3.0 and SATA Power Connectors

The TEP-1010-BSW has one internal SATA 3.0 connector (Marked C) for connecting to a SATA storage device. SATA Power connector (Marked B) is located next to it.

4.3. RTC Battery Connector

The TEP-1010-BSW features an internal RTC backup battery connector (Marked D).



Pin #	Signal	Description
1	GND	Ground
2	RTC_VCC	3V (connect to standard CR2032 battery)

Header on TEP-1010-BSW: Molex 53047-0210 (1.25mm Pitch PicoBlade Wire-to-Board Header). Cable receptacle: Molex 051021-8602 (1.25mm Pitch PicoBlade Wire-to-Wire and Wire-to-Board Housing) plug with crimp contact Molex 50058-8000. Battery P/N: KTS BCR2032H14.0AM1XB.

4.4. M.2 KEY-E Slot

The TEP-1010-BSW has one internal M.2 KEY-E connector: WIFI/BT (Marked E). M.2 WIFI/BT connector supports PCIe and USB 2.0 signals.

NOTE: M.2 WIFI/BT connector can be only used by a M.2 KEY-E Wi-Fi / BT module installed into the M.2 KEY-E connector (Marked E).

4.5. CMOS Jumper

To clear CMOS settings please turn the system off and disconnect the RTC battery (Marked D).



Pin #	Description
1-2	Default CMOS jumper settings
2-3	Clear CMOS jumper settings

Then short Pin #2 and Pin #3 of the 3-pin JCMOS1 header (Marked F) for 60 seconds, after which the CMOS will be restored to default factory settings. Restore default CMOS jumper settings before turning on the power.

4.6. SO-DIMM DDR3L Slot

The TEP-1010-BSW has one SO-DIMM DDR3L memory slot (Marked G).

4.7. Internal Stereo Speaker Connectors

The TEP-1010-BSW has two internal stereo speaker connectors to connect to two optional LEFT and RIGHT speakers (Marked J and I respectively). The signal is pre-amplified with a 2W Texas Instruments TPA2025D Class-D stereo audio amplifier.



LEFT Speaker connector (Marked J):

Pin #	Signal	Description
1	S_OUTL+	LEFT Speaker Positive Signal
2	S_OUTL-	LEFT Speaker Analog Ground Signal

RIGHT Speaker connector (Marked I):

Pin #	Signal	Description
1	S_OUTR+	RIGHT Speaker Positive Signal
2	S_OUTR-	RIGHT Speaker Analog Ground Signal

Header on TEP-1010-BSW: Molex 53047-0210 (1.25mm Pitch PicoBlade Wire-to-Board Header). Cable receptacle: Molex 051021-8602 (1.25mm Pitch PicoBlade Wire-to-Wire and Wire-to-Board Housing) plug with crimp contact Molex 50058-8000.

5. BIOS Setup

The BIOS (Basic Input / Output System) firmware comes pre-installed on the TEP-1010-BSW. The AMI UEFI BIOS is a non-volatile firmware used to perform hardware initialization during the booting process and provides a basic level of communication between the processor and peripherals. The BIOS setup program includes menus for configuring settings and enabling features of the TEP-1010-BSW.

NOTE: BIOS options listed here are for reference only. This section may reflect only the BIOS version corresponding to initial release and may differ from that of the purchased system.

5.1. Entering and Exiting BIOS

Enter BIOS setup by selecting DEL key when the system is powered on and the POST (Power On Self Test) message is displayed. Exit BIOS setup by selecting ESC key.

5.2. BIOS Setup Screens Overview

When BIOS is started, the main BIOS setup utility top-level screen appears. This screen provides six toplevel menu options across the top of the screen. The menu bar on top of the screen has the following main items:

Item	Screen Name	Description
#		
1	Main	Contain basic system information
2	Chipset	View the configuration of system chipsets
3	Advanced	Access advanced configuration options
4	Boot	Configure the boot device priority
5	Security	Set or change the administrator and user passwords
6	Save & Exit	Contain save and exit options

The highlighted item on the menu bar displays the specific items for that menu. Use the left and right arrow keys to select the different menu options. As you select each menu option, the top-level screen for that menu option appears. To select an option on a top-level screen, use the up and down arrow keys to scroll up and down the options presented. To display the submenu, select the item and press ENTER key. On sub-screens that only provide configuration information and cannot be modified, press the ESC key to exit the screen.

5.2.1. Main

By default, the Main screen appears when you enter the BIOS setup program. Main screen contains basic system information, including BIOS type, processor, memory, and time/date.

Main Chipset Advanced Boot Secur	rity Save & Exit	
BIOS Information BIOS Version Build Date and Time OnBoard LAN 1 MAC Address OnBoard LAN 2 MAC Address	TEP5-BSW RA1.1 10/19/2018 13:21:08 00-1F-7B-AA-01-66 00-1F-7B-AA-01-67	Set the Date. Use Tab to switch between Date elements.
System Information Intel(R) Pentium(R) CPU N3710 @ : Total Memory	1.60GHz 4096 MB (LPDDR3)	
System Date System Time	[Sun 01/01/2017] [00:01:14]	
Access Level	Administrator	t↓: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit

5.2.2. Chipset

The Chipset screens contain North Bridge and South Bridge configuration options.

Aptio Setup Utility – Copyright (C) 2018 American M Main <mark>Chipset</mark> Advanced Boot Security Save & Exit	Megatrends, Inc.
▶ North Bridge ▶ South Bridge	North Bridge Parameters
- - - - - - - - - - - - - - - - - - -	<pre>++: Select Screen t1: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit</pre>
Version 2.18.1264. Copyright (C) 2018 American Meg	gatrends, Inc.

5.2.3. Advanced

The BIOS Advanced screens provide detailed configuration information for the OS, POST Watchdog Timer, SATA, SDIO, Super IO, GPIO PORT and other system information.

NOTE: Setting incorrect or conflicting values in Advanced BIOS setup may cause system malfunction or inability to boot. Section <u>4.5. CMOS Jumper</u> provides instruction on clearing the CMOS and restoring default factory settings. The CMOS jumper can be found at location "F" chapter <u>4. Internal Connectors and Expansion Options</u> of this manual.

Aptio Setup Util Main Chipset Advanced Boot	ity – Copyright (C) 2018 Security Save & Exit	American Megatrends, Inc.
OS Config POST Watchdog Timer SATA Configuration SDIO Configuration Super IO Configuration GPIO PORT Config Hardware Monitor Smart Fan Configuration Wake Up Event Configuration Network Stack Configuration	[Default] O	OS Select: Default: ex. Windows 8,10 Legacy System: ex. Windows 7 Yocto Linux: Yocto Braswell **: Select Screen 11: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit
Version 2.18.12	64. Copyright (C) 2018 Am	erican Megatrends, Inc.

OS Config

Screen Name	Options	Description
OS Config	Default	Default: Windows 8, 10
	Legacy System	Legacy System: Windows 7
	Yocto Linux	Yocto Linux: Yocto Braswell

Super IO Configuration

Screen Name	Options	Description
Serial X Port	Enable	Enable or Disable Serial Port (COM)
	Disable	
Change Settings	Auto	Select an optimal setting for Super IO Device
	IO=3F8h; IRQ=4;	
	IO=3F8h;	
	IRQ=3,4,5,6,7,9,10,11,12;	
	IO=2F8h;	
	IRQ=3,4,5,6,7,9,10,11,12;	
	IO=3E8h;	
	IRQ=3,4,5,6,7,9,10,11,12;	
	IO=2E8h;	
	IRQ=3,4,5,6,7,9,10,11,12;	

GPIO PORT Config

Screen Name	Options	Description
GPIO PORT Config	GPIOXX Mode Select	Select input or output mode
	GPIOXX Value	Input Mode: Display input value Output Mode: Select output value

GPIO Control Address (TEP1010-xxxxx-Rxx-Lxxx-XG21-xxxx-xxxx)

Write IO port 0x2E -> 0x87 Write IO port 0x2E -> 0x87

Write IO port 0x2E -> 0x07 Write IO port 0x2F -> 0x06 Write IO port 0x2E -> 0xE0

```
Write IO port 0x2E -> 0xE1
Write IO port 0x2F -> // 0 : Output 0, 1 : Output 1 when in Output mode
BIT5 = GPIO15
```

Write IO port 0x2E -> 0x99 Write IO port 0x2F -> // 0 : Output 0, 1 : Output 1 when in Output mode BIT1 = GPIO91 BIT2 = GPIO92 BIT4 = GPIO94

Write IO port 0x2E -> 0xAA

GPIO Control Address (TEP1010-xxxxx-Rxx-Lxxx-XS21-xxxx-xxxx)

Write IO port 0x2E -> 0x87 Write IO port 0x2E -> 0x87

Write IO port 0x2E -> 0x07 Write IO port 0x2F -> 0x06 Write IO port 0x2E -> 0xE0 Write IO port 0x2F -> // 0 : Input mode, 1 : Output mode

BIT2 = GPIO12BIT5 = GPIO15BIT6 = GPIO16BIT7 = GPIO17Write IO port 0x2E -> 0xE1 Write IO port 0x2F -> // 0 : Output 0, 1 : Output 1 when in Output mode BIT2 = GPIO12 BIT5 = GPIO15BIT6 = GPIO16 BIT7 = GPIO17 Write IO port 0x2E -> 0x98 Write IO port 0x2F -> // 0 : Input mode, 1 : Output mode BIT1 = GPIO91 BIT2 = GPIO92BIT3 = GPIO93BIT4 = GPIO94Write IO port 0x2E -> 0x99 Write IO port 0x2F -> // 0 : Output 0, 1 : Output 1 when in Output mode BIT1 = GPIO91BIT2 = GPIO92 BIT3 = GPIO93 BIT4 = GPIO94

Write IO port 0x2E -> 0xAA

5.2.4. Boot

The Boot screens contain device priority boot options.

Aptio Setup Utility – O Main Chipset Advanced <mark>Boot</mark> Secu	Copyright (C) 2018 American rity Save & Exit	Megatrends, Inc.
Quiet Boot	[Enabled]	Enables or disables Quiet Boot
Bootup NumLock State Restore AC Power Loss CSM Support Network	[On] [Power Off] [Enabled] [UEFI]	option
Storage Other PCI devices	(UEFI) (UEFI)	
Boot Option Priorities Boot Option #1 Boot Option #2	[UEFI: JetFlashTrans] [JetFlashTranscend 4]	
Hard Drive BBS Priorities		<pre>++: Select Screen f↓: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit</pre>
Version 2.18.1264. Co	ouright (C) 2018 American M	egatrends. Inc.

Restore AC Power Loss

Screen Name	Options	Description
Restore AC Power Loss	Power Off	Select AC power state when power is re-
	Power On	applied after a power failure
	Last State	

Boot Option Priorities

Screen Name	Options	Description
Boot Option Priorities	Boot Option #1	Sets the system boot order
	Boot Option #2	

5.2.5. Security

The Security screens contain the administrator and user passwords settings.

Password Description Set Administrator Password If ONLY the Administrator's password is set, then this only asked for when entering Setup. Set Administrator Password If ONLY the User's password is set, then this is a power on password and must be entered to boot or enter Setup. In Setup the User will have Administrator rights. The password length must be in the following range: Minimum length 3 Maximum length 20 ++: Select Screen II: Select Item Enter: Select User Password User Password Set Administrator Setup. Administrator Password +*: Select Screen II: Select Item Enter: Select Version Password User Password Set Administrator Password F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	Aptio Setup Ut Main Chipset Advanced Bo	<mark>ility – Copyright (C) 2018 American</mark> ot <mark>Security Save & Exit</mark>	Megatrends, Inc.
then this only limits access to Setup and is only asked for when entering Setup. If ONLY the User's password and must be entered to boot or enter Setup. In Setup the User will have Administrator rights. The password length must be in the following range: Minimum length 3 Maximum length 20 ++: Select Screen 11: Select Item Enter: Select User Password User Password Setup the User will Administrator Password User Password Setup the User Will the User will Administrator Password User Password Setup the User Will the User Will Setup the User Will	Password Description	nassword is set	Set Administrator Password
If ONLY the User's password is set, then this is a power on password and must be entered to boot or enter Setup. In Setup the User will have Administrator rights. The password length must be in the following range: Minimum length 3 Maximum length 20 ++: Select Screen 14: Select Item Enter: Select User Password User Password F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	then this only limits access	to Setup and is Setup.	
bot or enter Setup. In Setup the User will have Administrator rights. The password length must be in the following range: Minimum length 3 Maximum length 20 ++: Select Screen 11: Select Item Enter: Select User Password +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	If ONLY the User's password	is set, then this	
have Hdministrator rights. The password length must be in the following range: Minimum length 3 Maximum length 20 ++: Select Screen 11: Select Item Enter: Select User Password User Password F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	boot or enter Setup. In Setup	o the User will	
in the following range: Minimum length 3 Maximum length 20 Administrator Password User Password H: Select Screen 11: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	The password length must be		
Maximum length20Administrator Password++: Select ScreenUser PasswordEnter: Select+/-: Change Opt.F1: General HelpF2: Previous ValuesF3: Optimized DefaultsF4: Save & ExitESC: Exit	in the following range: Minimum length	3	
Administrator Password User Password User Password H1: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	Maximum length	20	
User Password +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	Administrator Password		†↓: Select Item Enter: Select
F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit	User Password		+/-: Change Opt.
F3: Optimized Defaults F4: Save & Exit ESC: Exit			F2: Previous Values
ESC: Exit			F3: Uptimized Defaults F4: Save & Exit
			ESC: Exit

5.2.6. Save & Exit

The Save & Exit screens contain save and exit options.

Save Changes and Reset Discard Changes and Reset Restore Defaults	Reset the system after saving the changes.
	<pre>++: Select Screen 14: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit</pre>

Restore Defaults

Screen Name	Options	Description
Restore Defaults	Save Changes and Reset	Save changes and exit, discard changes and exit, or discard changes
	Discard Changes and Reset	
	Restore Deaults	

6. Mounting

This section describes the mounting procedures for the TEP-1010-BSW. The material in area of the mounting must provide sufficient strength for safe mounting of this device.

6.1. VESA Mounting

The TEP-1010-BSW is compatible with the VESA MIS-D Standard 100*100mm hole pattern. There are 4 VESA MIS-D (M4) mounting holes on the rear side of the device. M4 screw holes are a depth of 6mm.



6.2. Rear Mounting and Mounting Clips Installation

There are 7 mounting clips required for rear mounting.



Please follow the steps below to secure the clips. Prepare mounting hook, post and screw (M3) (Step 1). Locate all removable tabs on the rear side of your device and use pincers or pliers to remove the tabs (Step 2-3). Press the mounting clip into the holes at an angle and slowly straighten it (Step 4-5). Then tighten the screw to the surface (Step 6). Repeat the steps for all clips required to secure your device.



6.3. Surface Mounting

There are 10 mounting holes (M4) on the rear side of the device required for surface mounting. M4 screws with at least 6mm head-to-tip length are required to secure this device.



7. Ordering Information

The TEP-1010-BSW is available in several configurations. Please contact your TechNexion sales contact window or distributor for options and availability details.

7.1. Custom Part Number Rule

The TEP-1010-BSW can be ordered in custom tailored configuration to meet special application requirements and conditions according to the following custom part number creation rules. Custom part numbers carry minimum order quantities (MOQ). Please connect with your TechNexion distributor or account manager for conditions and availability. Part number format:

Interface	Code	Description
Processor	E8000	Intel Atom x5-E8000
	N3710	Intel Pentium N3710
Memory	R20	2GB SO-DIMM DDR3L
	R40	4GB SO-DIMM DDR3L
	R80	8GB SO-DIMM DDR3L
Power Expansion	L112	TXR-P1-12V-LAN1 (12V 3A)
	L124	TXR-P1-24V-LAN1 (24V 3A)
	L130	TXR-P1-1030V-LAN1 (8-36V 5A)
	LPOE	TXR-P1-12V-POE1 (12V 3A) or (PoE 802.3at)
I/O Expansion	-	-
	XS21	2x RS-232 + 8x GPIO
	XG21	2x RS-232 + 8x GPIO (Galvanic Isolated)
Storage	-	-
	M064	64GB M.2 SSD
	S064	64GB 2.5" SATA SSD
Internal Speaker	-	-
	SPK	2x 2W/8Ω Stereo Speaker
Custom ID	XXXX	Custom Part number ID for customized software loader and special component (BOM)

TEP1010-xxxxx-Rxx-Lxxx-xxxx-xxxx-xxxx

7.2. Standard Package Contents



Item	Partnumber	Description	
1	TEP-1010-BSW	10 inch PoE HMI PCAP touch system with Intel Braswell	
2	Accessoires	7x mounting hooks	
		7x short screws (M3)	
		7x mounting posts	
		2x Wi-Fi/LTE module screw	
		2x screw (M3) for M.2 card	
		2x plastic washer	
		1x DC power latch cable (2-pin Micro-Fit 3.0)	

NOTE: Pack contents might vary depending on your ordered configuration.

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